

EMC 와 Ag 도금된 leadframe 표면의 접착효과에 관한 Plasma 처리의 영향 (Effect of plasma treatment on adhesion of EMC and Ag plated leadframe)

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Abstract: In the Quad Flat Package(QFP), Ag plated die pad area for ground bond have poor adhesion property with Epoxy Molding Compound(EMC). So delamination was found after reflow at Ag plated boundary die pad area in the QFP. Fused & Double Down Set ring leadframe design have been used to solve delamination issue. These special designs have higher manufacturing cost and impact cost on the packaging. Plasma is an effective process to improve adhesion without cost up and design change of leadframe. In this study, Ar, Air gas plasma is used to improve adhesion property. As the results of study, plasma treatment increases adhesion but couldn't achieve no delamination.